

# Engineering Interface Defects and Interdiffusion at the Degenerate Conductive $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$ Interface for Stable Electrodes in a Saline Solution

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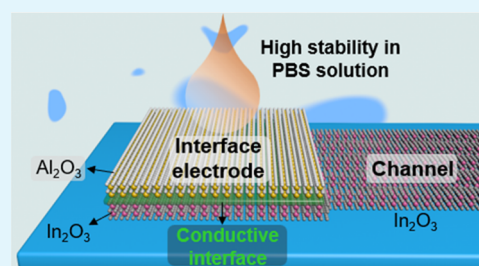
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**ABSTRACT:** A low-temperature  $\text{Al}_2\text{O}_3$  deposition process provides a simplified method to form a conductive two-dimensional electron gas (2DEG) at the metal oxide/ $\text{Al}_2\text{O}_3$  heterointerface. However, the impact of key factors of the interface defects and cation interdiffusion on the interface is still not well understood. Furthermore, there is still a blank space in terms of applications that go beyond the understanding of the interface's electrical conductivity. In this work, we carried out a systematic experimental study by oxygen plasma pretreatment and thermal annealing post-treatment to study the impact of interface defects and cation interdiffusion at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface on the electrical conductance, respectively. Combining the trends in electrical conductance with the structural characteristics, we found that building a sharp interface with a high concentration of interface defects provides a reliable approach to producing such a conductive interface. After applying this conductive interface as electrodes for fabricating a field-effect transistor (FET) device, we found that this interface electrode exhibited ultrastability in phosphate-buffered saline (PBS), a commonly used biological saline solution. This study provides new insights into the formation of conductive 2DEGs at metal oxide/ $\text{Al}_2\text{O}_3$  interfaces and lays the foundation for further applications as electrodes in bioelectronic devices.

**KEYWORDS:** 2DEG, conductive interface, interface engineering, interface electrode, stability in biological saline



## 1. INTRODUCTION

The heterointerfaces between two different insulating oxide materials can exhibit interfacial superconductivity different from that of either component, which is attributed to the formation of a conductive two-dimensional electron gas (2DEG) at the interface.<sup>1–5</sup> Experimental and theoretical studies of the 2DEG interface between two oxide insulators,  $\text{LaAlO}_3$  (LAO) and  $\text{SrTiO}_3$  (STO), have revealed intriguing physical phenomena, such as superconductivity,<sup>6–8</sup> magnetic interaction,<sup>9–11</sup> field-tunable metal–insulator transition,<sup>3,12</sup> and quantized transport.<sup>13,14</sup> However, the 2DEG formed at the epitaxial interface of the LAO/STO requires harsh fabrication conditions, for example, LAO layers must be grown on Ti-terminated STO single-crystalline substrates at high temperatures by pulsed laser deposition or molecular beam epitaxy.<sup>15–20</sup> There are other examples: the conductivity<sup>21–25</sup> or mobility<sup>26–30</sup> in many functional electronic devices should be controlled by engineering processes, such as impurity doping,<sup>31,32</sup> and lithography and etching processes are required for the device fabrications.<sup>15,21,27</sup> Such complex engineering and processing steps limit 2DEG practical applications in functional electronic devices. Thus, current research on the 2DEG conductive heterointerface has mainly been limited to the study of its physical phenomena, but there

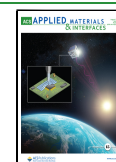
has been no significant progress in the design and processing of electronic devices.

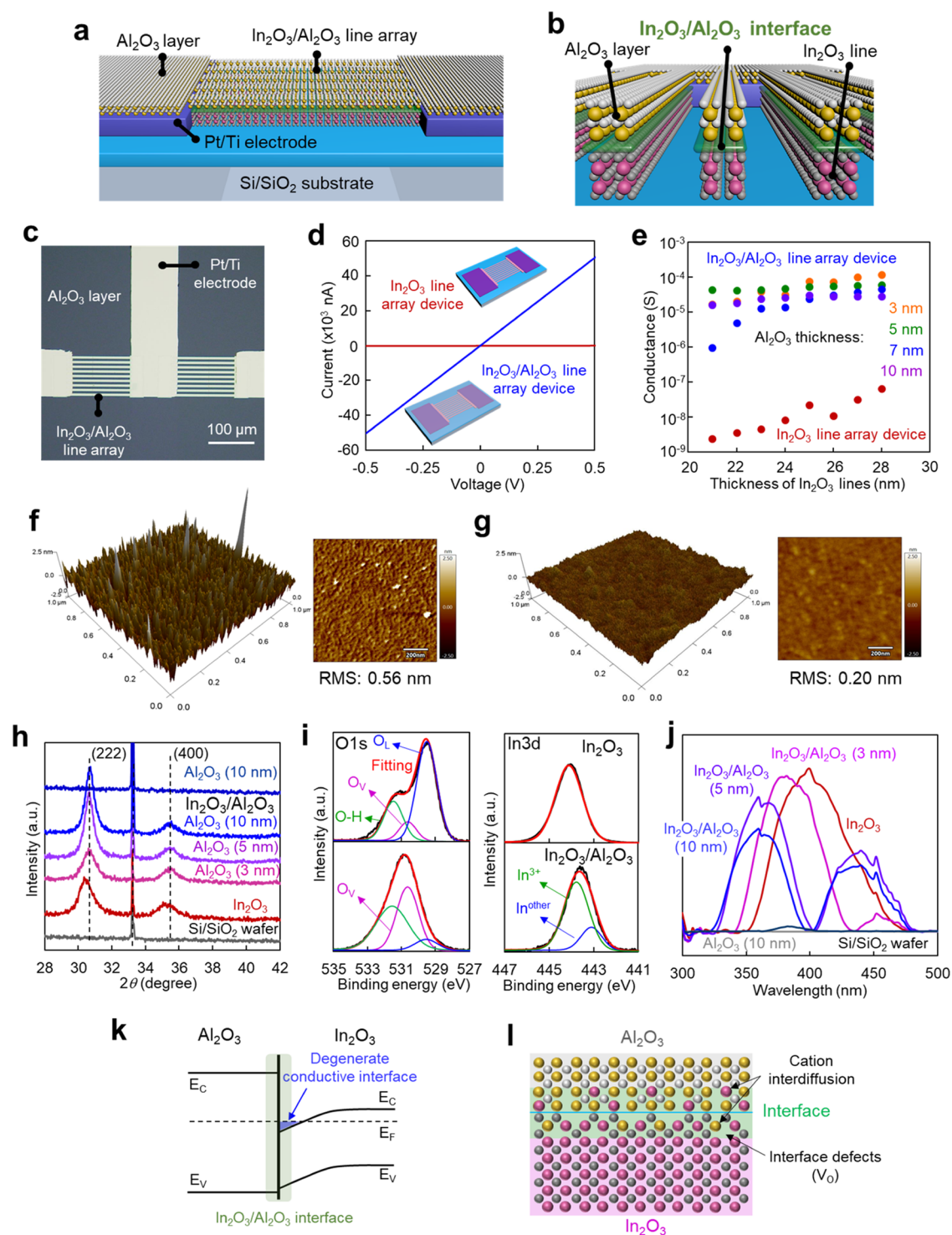
Recently, a simplified  $\text{Al}_2\text{O}_3$  deposition process by atomic layered deposition (ALD) at low temperatures ( $<300\text{ }^\circ\text{C}$ ) was found to form the conductive 2DEG interface, overcoming the harsh preparation conditions of the LAO/STO system and providing a way to design and engineer this conductive heterointerface.<sup>33–37</sup> Among ALD of  $\text{Al}_2\text{O}_3$  layers on single or polycrystalline metal oxide layers, several types of conductive heterointerfaces have been fabricated, including  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$ ,<sup>33,34</sup>  $\text{ZnO}/\text{Al}_2\text{O}_3$ ,<sup>35</sup>  $\text{WO}_3/\text{Al}_2\text{O}_3$ ,<sup>36</sup> and  $\text{TiO}_2/\text{Al}_2\text{O}_3$ .<sup>37,38</sup> The two main factors responsible for the formation of conductive 2DEGs at the heterointerface are oxygen vacancies ( $V_{\text{O}}$ ) at the interface and cation interdiffusion at the interface.<sup>34,36–38</sup> A representative study directly analyzed the chemical composition of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface by combining cross-sectional high-resolution transmission elec-

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**Figure 1.** Fabrication of the degenerate 2DEG at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  heterointerface. (a) Schematic of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device. (b) Schematic of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface. (c) Example microscopy image of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device. The scale bar is 100  $\mu\text{m}$ . (d)  $I$ - $V$  curves of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array devices. (e) Conductance of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array devices when varying the thicknesses of  $\text{In}_2\text{O}_3$  and  $\text{Al}_2\text{O}_3$ . (f, g) Atomic force microscopy (AFM) images of the  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers. (h) X-ray diffraction (XRD) patterns of  $\text{Al}_2\text{O}_3$ ,  $\text{In}_2\text{O}_3$ , and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers with different  $\text{Al}_2\text{O}_3$  thicknesses and  $\text{Si}/\text{SiO}_2$  substrate. (i) XPS spectra of the  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers. (j) Photoluminescence (PL) spectra of  $\text{In}_2\text{O}_3$ ,  $\text{Al}_2\text{O}_3$ , and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers with different  $\text{Al}_2\text{O}_3$  thicknesses and  $\text{Si}/\text{SiO}_2$  substrate. (k) Estimated band alignment diagram of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface, which demonstrates the degenerate conductive interface. (l) Schematic of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface, which describes the interface defects and interdiffusion.

tron microscopy (HR-TEM), electron energy loss spectroscopy (EELS), and depth-resolved X-ray photoelectron spectroscopy (XPS) techniques and proposed a formation mechanism model for a 2DEG conducting path at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$

interface.<sup>34</sup> However, the relationship between the chemical composition and electrical conductivity cannot be directly illustrated by an analysis of the chemical composition of an individual interface. No systematic and dynamic experimental

study has been made to demonstrate the impact of key factors of interface defects and cation interdiffusion on the formation of this conductive interface. In addition, engineering this conductive 2DEG interface and exploring its applications in functional electronic devices have not yet been carried out.

In this work, based on current knowledge of the conductive 2DEG at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface, we conducted a systematic experimental study using oxygen plasma pretreatment and thermal annealing post-treatment to respectively engineer interface defects and cation interdiffusion at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface and further understanding of the formation mechanism of the conductive interface. By engineering different interfaces, we found that the interfacial defects facilitated the formation of the degenerate conductive interface, while cation interdiffusion at this interface degraded it. This implies that the thickening of the cation interdiffusion layer is detrimental to the formation of the conductive interface, which is different from past results. Considering the advantages of the conductive interface with a highly stable upper  $\text{Al}_2\text{O}_3$  layer, this interface was processed as the electrodes in a field-effect transistor (FET) device and exhibited high stability in the PBS solution. This result represents the first realization of a 2DEG-based conductive interface electrode in an electronic device and shows potential for further applications in bioelectronic devices.

## 2. EXPERIMENTAL SECTION

**2.1. Fabrication of an  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  Line Array Device and an FET Device.** An  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device (Figure 1a) was fabricated on a  $\text{Si}/\text{SiO}_2$  ( $\text{SiO}_2$  layer: 100 nm thick) substrate using the typical lithography method described in our previous reports.<sup>39–42</sup> In all our fabrications, the  $\text{In}_2\text{O}_3$  layer was deposited by radio frequency (RF) sputtering and the deposition rate was about 5 nm/min (Figure S1a). We obtained 20–30 nm thick  $\text{In}_2\text{O}_3$  lines by controlling the deposition time. The  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array was obtained by depositing an  $\text{Al}_2\text{O}_3$  layer on the  $\text{In}_2\text{O}_3$  lines using ALD. The Al source of trimethylaluminum (TMA) and O source of water were used to form a thin  $\text{Al}_2\text{O}_3$  (3–10 nm) layer at 150 °C. The fluxes of TMA and water were controlled by the deposition times of 0.015 and 0.1 s, respectively.

A back-gated FET device with a line array channel was fabricated by adding a back-gated electrode on the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device. More specifically, a hole was made in the  $\text{SiO}_2$  layer on the  $\text{SiO}_2/\text{Si}$  substrate at an edge position of the device to get direct contact between the Pt/Ti electrode and the Si layer below the  $\text{SiO}_2$  layer.

**2.2. Fabrication of an  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  Interface Electrode Device.** An  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device was fabricated using  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  as the electrode and  $\text{In}_2\text{O}_3$  as the channel. First, a large pattern with regions of both the line array and electrodes (Figure 1b) was prepared by the lithography technique. The patterned  $\text{In}_2\text{O}_3$  layer was obtained by depositing  $\text{In}_2\text{O}_3$  using RF sputtering. Then, a small pattern with the photoresist only at the position of the  $\text{In}_2\text{O}_3$  line array was obtained using the second lithography step. Next, the  $\text{Al}_2\text{O}_3$  layer was deposited in 40 cycles by ALD at 150 °C. The device was immersed in acetone to remove the photoresist above the line array. Last, IPA washing and  $\text{N}_2$  flow drying were performed to get a clean device. In this case, a window in the  $\text{Al}_2\text{O}_3$  layer at the  $\text{In}_2\text{O}_3$  line array region was obtained. The  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  region acts as the electrode, while the  $\text{In}_2\text{O}_3$  line array in the window region acts as the channel.

**2.3. Characterizations.** The structure of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device was observed using optical microscopy images (Figure 1c). The crystalline phases of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers were measured by X-ray diffraction (XRD, Rigaku Miniflex 600). The interdiffusion at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface was analyzed from the XRD pattern. The valence band and defects of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/$

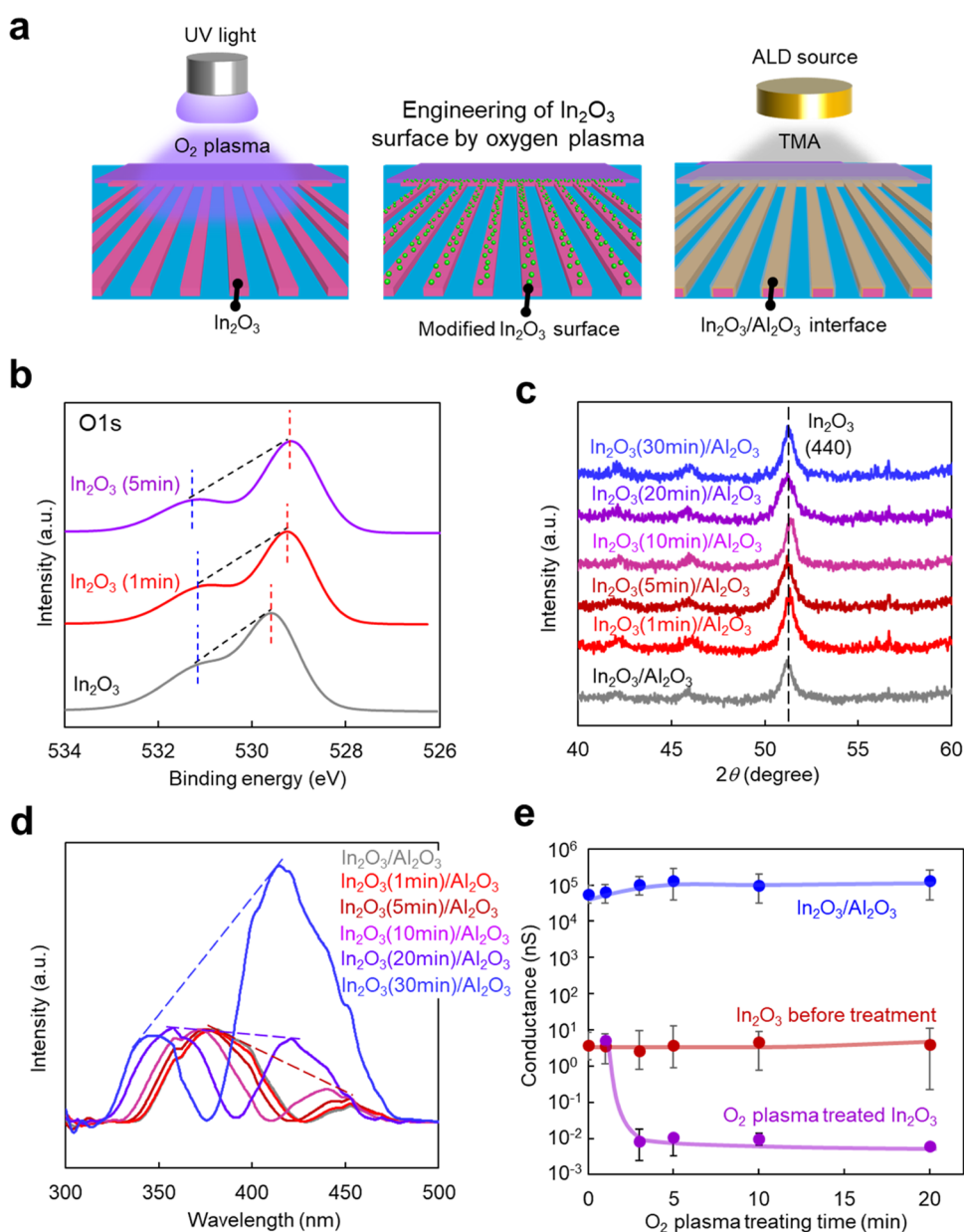
$\text{Al}_2\text{O}_3$  layers were characterized by photoluminescence (PL) spectra, which were measured using a fluorescent spectrophotometer (JASCO FP-8600) equipped with a xenon lamp as the excitation source. The excitation wavelength was set to 280 nm. The deposition rate of the  $\text{In}_2\text{O}_3$  layer was characterized using a field-emission scanning electron microscope (FESEM, Zeiss Supra 40 VP) at an accelerating voltage of 15 kV. The surface profile was characterized by an atomic force microscope (AFM, MFP-3D Origin, Oxford Instruments). The chemical composition of the  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers was investigated by X-ray photoelectron spectroscopy (XPS, ULVAC-PHI VersaProbe III) with an Al  $K\alpha$  radiation ( $h\nu = 1486.6$  eV). Raman spectra were conducted using a spectrometer (LabRAM HR800, HORIBA JobinYvon) with an excitation laser wavelength of 514.5 nm.

**2.4. Electrical Measurements.** The current–voltage ( $I$ – $V$ ) curve, transfer curve, and UV photoresponse (365 nm) were measured by two connected semiconductor parameter analyzers (Keithley, Model 2401). All of the measurements were done at room temperature.

## 3. RESULTS AND DISCUSSION

**3.1. Formation of Degenerate 2DEG at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  Heterointerface.** Figure 1a,b shows schematics of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device and the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface, respectively. An array of nine  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  lines with a width of 5  $\mu\text{m}$  and a length of 120  $\mu\text{m}$  served as the electron transport channel of the device (Figure 1c). The current–voltage ( $I$ – $V$ ) curves show that the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array device possessed higher conductivity than the  $\text{In}_2\text{O}_3$  line array device (Figure 1d). To evaluate the enhanced conductivity, the conductance of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line arrays of various line thicknesses was calculated based on the  $I$ – $V$  curves (Figure 1e). Compared to the  $\text{In}_2\text{O}_3$  line array, the conductance of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array was approximately 4 orders of magnitude higher. As both the  $\text{In}_2\text{O}_3$  line array and  $\text{Al}_2\text{O}_3$  layer maintained low conductance during the ALD process (Figure S3), we confirmed that the enhanced conductance of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array originated from the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface.

To understand the reason for the high electrical conductivity at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface, we analyzed the structure, chemical composition, and electrical transport behavior of the  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers. From the AFM images (Figure 1f,g), we observed that the surface of the film has been smoother after depositing the  $\text{Al}_2\text{O}_3$  layer. As shown in XRD patterns, the diffraction peaks of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers were shifted toward a higher  $2\theta$  angle in comparison with the  $\text{In}_2\text{O}_3$  layer (Figure 1h), while the diffraction peak of the Si substrate remained unshifted. This shift behavior could be attributed to the formation of a new phase of the intermixing layer at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface owing to the atom interdiffusion.<sup>43–45</sup> As shown in the XPS spectra of Figure 1i, two peaks attributed to the O 1s spectrum located between 527 and 535 eV were replaced by a broad peak at 439.9 eV. By fitting the spectrum based on three chemical binding states, including oxygen lattice ( $\text{O}_L$ ), oxygen vacancy ( $\text{O}_V$ ), and hydroxyl ( $-\text{O}-\text{H}$ ),<sup>34,46,47</sup> we suggested that a large amount of  $\text{O}_V$  was generated close to the interface during its formation. We also made a simplified fitting of the In 3d spectrum using two binding states, the stable In state ( $\text{In}^{3+}$ ), and the other In state ( $\text{In}^{\text{other}}$ ).<sup>34,46,47</sup> The shift of the In 3d spectrum indicated a change in the In-related binding state, which was caused by the interactions of In, O, and Al atoms at the interface. In combination with the XRD results, we believe that this peak shift was caused by the interdiffusion of atoms at the interface.

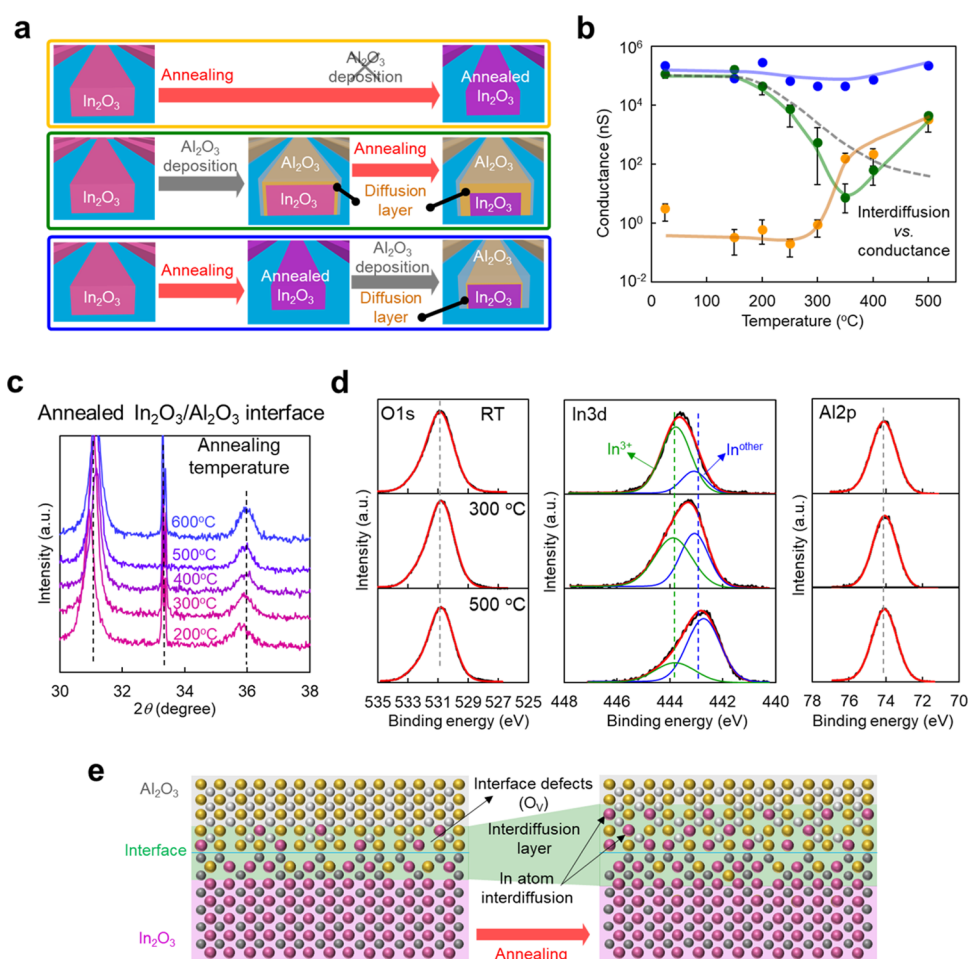


**Figure 2.** Engineering the interface defects of the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> interface. (a) Schematics of pretreatment of the In<sub>2</sub>O<sub>3</sub> surface prior to Al<sub>2</sub>O<sub>3</sub> deposition. (b) XPS spectra of the In<sub>2</sub>O<sub>3</sub> layer with different oxygen plasma pretreatment times. (c) XRD patterns of In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> layers with different oxygen plasma pretreatment times of the In<sub>2</sub>O<sub>3</sub> surface. (d) PL spectra of In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> layers with different oxygen plasma pretreatment times of the In<sub>2</sub>O<sub>3</sub> surface. (e) Conductance of In<sub>2</sub>O<sub>3</sub> and In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> line arrays with different oxygen plasma pretreatment times of the In<sub>2</sub>O<sub>3</sub> surface.

In addition, we found that on the In<sub>2</sub>O<sub>3</sub> layer, the near-band-edge (NBE) emission peak shifted toward lower wavelengths from 402 to 361 nm after depositing the Al<sub>2</sub>O<sub>3</sub> layer, which was consistent with a Burstein–Moss shift due to conduction band filling of the carriers (Figure 1j).<sup>4</sup> This suggested that high-concentration carriers were localized at the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> interface that formed a metallic degenerate conductive interface, which can be described in terms of a 2DEG (Figure S4).<sup>4,34,35,38</sup>

Finally, transfer curves of the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> line array, which was the “normally on” state, also indicated that the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> interface exhibited a conductive property with a high carrier concentration, while In<sub>2</sub>O<sub>3</sub> exhibited the typical semiconductor property (Figure S5).<sup>48</sup> Furthermore, UV photoresponse provided other indirect evidence of the

conductive property of the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> line array (Figure S6). While the In<sub>2</sub>O<sub>3</sub> line array showed a current response to UV light of two orders of magnitude, the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> line array maintained an almost constant current, even when the effect of high current compared to the In<sub>2</sub>O<sub>3</sub> line array was eliminated by applying a low voltage of 0.001 V. This indicated that the enhancement of the current by UV-excited photoelectrons in the In<sub>2</sub>O<sub>3</sub> line array was almost negligible compared to the high concentration of electrons at the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> interface.<sup>49</sup> In addition, the flat subthreshold slope of the transfer curve and slow photoresponse observed from the electrical measurements indicated a low carrier mobility at the interface.<sup>48,49</sup> This result also demonstrated that the enhanced conductivity of the interface was caused by the high carrier concentration. All of the interpretations of the



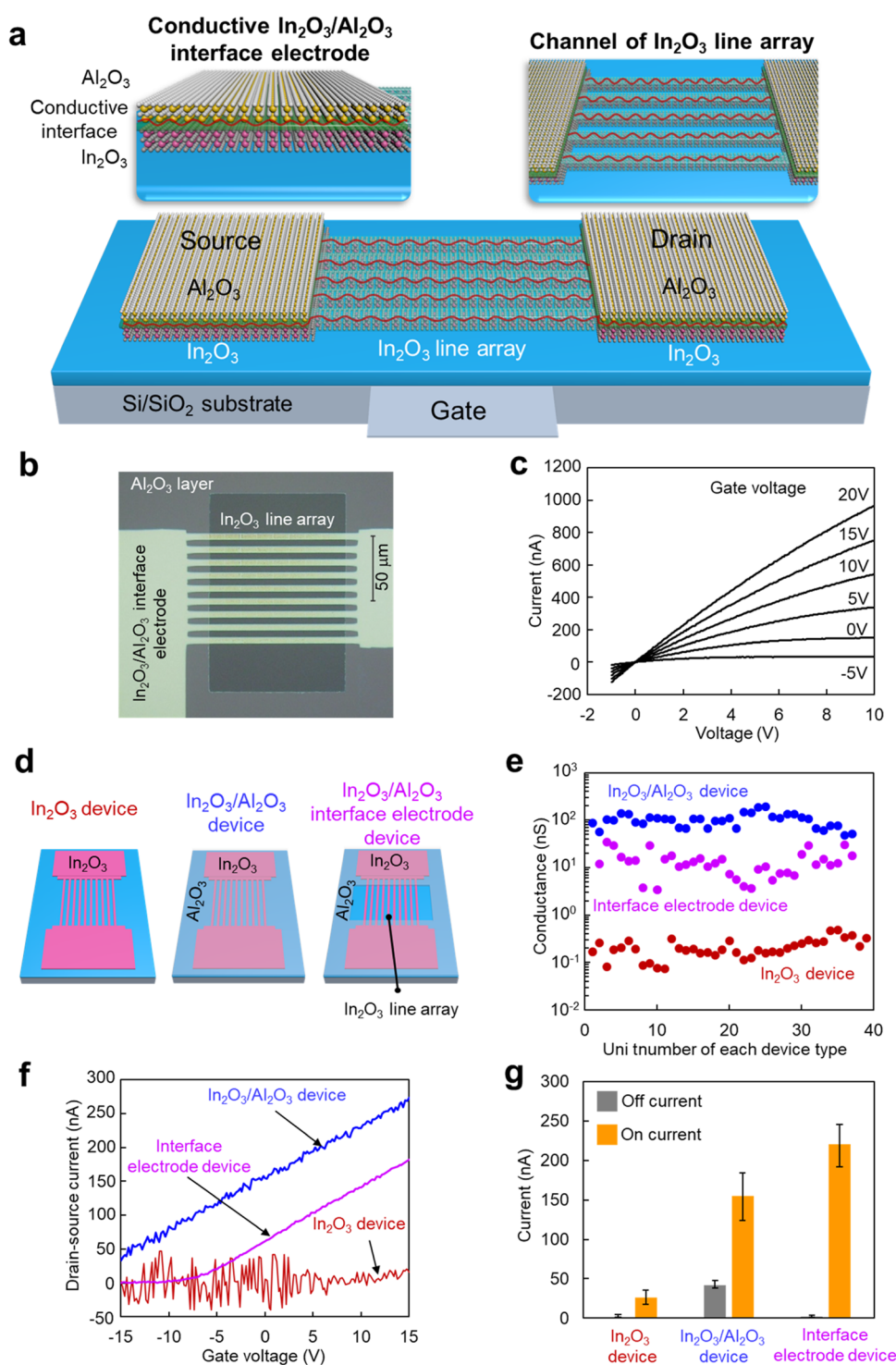
**Figure 3.** Engineering the interdiffusion of the  $\text{Al}_2\text{O}_3/\text{In}_2\text{O}_3$  interface. (a) Schematic of three kinds of annealing processes of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line arrays. (1) Yellow box:  $\text{In}_2\text{O}_3$  line arrays were annealed at different temperatures. (2) Blue box: first,  $\text{In}_2\text{O}_3$  line arrays were annealed at different temperatures, followed by deposition of  $\text{Al}_2\text{O}_3$  by ALD. (3) Green box: first,  $\text{Al}_2\text{O}_3$  was deposited by ALD on the  $\text{In}_2\text{O}_3$  line array, followed by annealing at different temperatures. (b) Annealing temperature-dependent conductance of  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line arrays in three kinds of annealing processes. The annealing conditions for the different colored curves correspond to the colored boxes in Figure 4a. The gray dashed line shows the estimated curve of interdiffusion-dependent conductance. (c) XRD patterns of  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers annealed at different temperatures in air. (d) XPS spectra of  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers annealed at different temperatures in air. (e) Schematic of the model for the interdiffusion-dependent conductive  $\text{In}_2\text{O}_3$  and  $\text{Al}_2\text{O}_3$  interface.

above data suggested that this conductive  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface was a degenerate 2DEG with a high carrier concentration, which was described by the band diagram of Figure 1k.<sup>50–52</sup>

Currently, the three most accepted scenarios to describe the mechanism of 2DEG formation using amorphous  $\text{Al}_2\text{O}_3$  are a polar catastrophe, cation interdiffusion, and oxygen vacancy ( $\text{V}_\text{o}$ ) generation at the interface.<sup>34,38</sup> Based on the analysis of structure, composition, and electrical transport behavior of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layer, we suggested that the interface defects ( $\text{V}_\text{o}$ ) and cation interdiffusion at the interface were crucial factors in the formation of such a conductive  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface. However, the relationship between the structure, chemical composition, and electrical conductivity cannot be easily demonstrated by analysis of an individual interface. Therefore, to further understand this conductive  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface, we undertook systematic experiments, in which we engineered interface defects and cation interdiffusion at the interface, as depicted in the schematic of Figure 1l. In addition, by engineering the above factors, we were seeking an approach to control this conductive interface, for example, to get a more

stable fabrication method, to gain a higher conductivity enhancement, etc.

**3.2. Engineering Interface Defects of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  Heterointerface.** First, we considered the formation and engineering of interface defects at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface using an  $\text{In}_2\text{O}_3$  surface pretreated by oxygen plasma before  $\text{Al}_2\text{O}_3$  deposition (Figure 2a). This is because the oxygen plasma treatment generally enhances the number of hydrophilic groups on metal oxide surfaces, especially for hydroxyl groups,<sup>53</sup> which may affect the generation of interface defects at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface during ALD. As seen in the XPS spectra (Figure 2b), the O 1s peak located at 529.6 eV shifted toward a lower energy direction after the oxygen plasma pretreatment in  $\text{In}_2\text{O}_3$  layers, suggesting that the binding state changed from the  $\text{O}_\text{V}$  state to the  $\text{O}_\text{L}$  state. This is caused by the oxidation of oxygen-deficient  $\text{In}_2\text{O}_3$  during the oxygen plasma treatment.<sup>54</sup> A slight shift of the peak located at 531.2 eV indicated an increase of the O–H bonding on the surface. In other words, the hydroxyl groups on the surface were increased by oxygen plasma treatment. The crystalline phase of  $\text{In}_2\text{O}_3$  was confirmed by the XRD pattern, and no peak shift



**Figure 4.** Processing the conductive  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface as the interface electrode. (a) Schematic of the FET device with the  $\text{In}_2\text{O}_3$  line array as the electron transport channel and the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  conductive interface as the interface electrode. (b) Microscopy image of the device. A window was opened at the  $\text{In}_2\text{O}_3$  line array region to fabricate the device. (c) Representative output curves of the device with gate voltage as a function. The drain-source voltage was 1 V. (d) Schematic of three kinds of devices. (1) The  $\text{In}_2\text{O}_3$  device is patterned  $\text{In}_2\text{O}_3$  with the  $\text{In}_2\text{O}_3$  line array as the transport channel and  $\text{In}_2\text{O}_3$  as the electrode. (2) The  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  device is patterned  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  with the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array as the transport channel and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  as the electrode. (3) The  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device is patterned  $\text{In}_2\text{O}_3$  with the  $\text{In}_2\text{O}_3$  line array as the transport channel and the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  as the electrode. (e) Measured conductance of the  $\text{In}_2\text{O}_3$  device,  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  device, and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device. (f) Transfer curves of the  $\text{In}_2\text{O}_3$  device,  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  device, and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device. The drain-source voltage is 1 V. (g) Comparison of "on" current (applied gate voltage: 10 V) and "off" current (applied gate voltage: -10 V) of the  $\text{In}_2\text{O}_3$  device,  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  device, and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device.

was observed (Figure 2c). In contrast to the XRD results in Figure 1h, which indicated that the shift of the peaks was

caused by interdiffusion, interdiffusion at the interface was not changed by the oxygen plasma pretreatment. When oxygen

plasma treatment time was increased, a blue shift in the NBE peak of the pretreated  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers (implying degenerate character) was observed and the peak ratio of the defect and NBE peaks increased, as shown in the PL spectra of Figure 2d. This means that the degenerate interface with additional defects might also be formed when the oxygen plasma pretreatment was applied.<sup>4</sup>

In addition, the conductance of  $\text{In}_2\text{O}_3$  line arrays decreased with increasing oxygen plasma treatment time, while the conductance of  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line arrays increased slightly (Figure 2e). Based on the analysis of the above characterization, we believe that two factors contributed to the reduction of the conductivity of the  $\text{In}_2\text{O}_3$  layer by oxygen plasma treatment: (1) reducing the conductive oxygen vacancies in the metal oxide<sup>54</sup> and (2) increasing the number of surface hydroxyl groups that trap carriers. Since the conductance of the oxygen plasma pretreated  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface always increased after  $\text{Al}_2\text{O}_3$  deposition, we speculated that the oxygen vacancies were refilled during the ALD process or the oxygen vacancies within the  $\text{In}_2\text{O}_3$  body produced a tiny effect on interface conductance.<sup>54</sup> This is because the reduction of the oxygen vacancies generally reduces the electrical conductivity. Therefore, we have ignored the effect of oxygen vacancy fluctuations and focused on the effect of the increased numbers of hydroxyl groups on the  $\text{In}_2\text{O}_3$  surface. In this case, the conductance of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array increased with increasing pretreatment time, which could be attributed to the increase in shallow-level interface defects (e.g., oxygen vacancies), as the interdiffusion remained unchanged during the process. This means the hydroxyl groups on the  $\text{In}_2\text{O}_3$  surface might facilitate the generation of shallow-level interface defects during the ALD of the  $\text{Al}_2\text{O}_3$  layer. Although the formation mechanism of these shallow-level interface defects was not clear, we can conclude that the groups generated on the  $\text{In}_2\text{O}_3$  surface by the oxygen plasma treatment will promote the generation of conductive interface defects, leading to increased conductance of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface. Therefore, the interface defects that facilitate the formation of such degenerate conductive interfaces can be engineered by oxygen plasma pretreatment, and these defects can further increase the conductivity of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface.

**3.3. Engineering Interdiffusion of the  $\text{Al}_2\text{O}_3/\text{In}_2\text{O}_3$  Heterointerface.** Next, we considered if interdiffusion occurred at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface during the ALD of the  $\text{Al}_2\text{O}_3$  layer and if it could be engineered by a postannealing process, as thermal annealing always facilitates atom diffusion.<sup>55–57</sup> The effect of interdiffusion at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface on the electrical conductance was investigated by altering the sequence of  $\text{Al}_2\text{O}_3$  deposition and thermal annealing treatment. Three kinds of annealing processes were conducted as summarized in Figure 3a. Diffraction peaks of XRD patterns were gradually shifted toward the higher angle direction by increasing the annealing temperature from 200 to 600 °C (Figure 3c), indicating that the interdiffusion at the interface can be controlled by the annealing process.

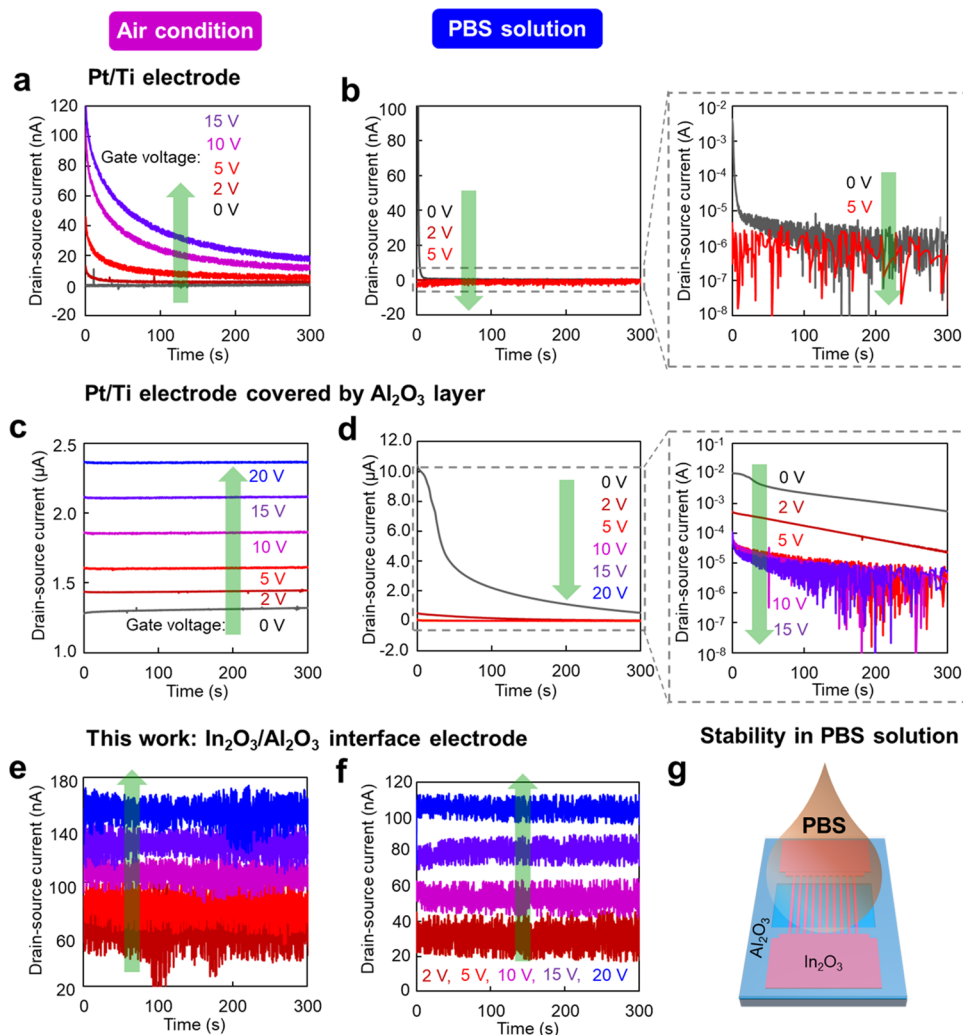
Temperature-dependent conductance showed that the conductance of the  $\text{In}_2\text{O}_3$  line array increased with annealing temperature from 250 to 500 °C, which is generally due to the generation of shallow-level defects, such as oxygen vacancies or indium interstitial defects.<sup>58,59</sup> When directly annealing the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array, the conductance decreased first and increased above 350 °C. To clarify the trend of this variation,

we measured the XPS spectra of  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  layers annealed at 300 and 500 °C, as shown in Figure 3d. The In 3d peak shifted toward lower energies with increasing annealing temperature, while the O 1s and Al 2p peaks remained at 539.9 and 74.2 eV, respectively.<sup>60,61</sup> This indicated that the change in the In binding state played a dominant role compared to the change in the oxygen and Al binding states. Based on the fitting results of the In 3d peak, in which the binding state of  $\text{In}^{3+}$  was converted to  $\text{In}^{\text{other}}$ , we speculated that the interdiffusion of In at the interface was the main behavior and led to a decrease in conductance, as shown in the schematic of Figure 3e. The conductance increased above 350 °C was due to the increased conductance of the  $\text{In}_2\text{O}_3$  line array.

In addition, when  $\text{Al}_2\text{O}_3$  was deposited by ALD after annealing the  $\text{In}_2\text{O}_3$  line array, the  $\text{In}_2\text{O}_3$  line array with enhanced crystallization would prevent the interdiffusion of  $\text{Al}_2\text{O}_3$  during the ALD. The conductance of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  line array remained consistently high and increased slightly above 300 °C, which agreed with the enhanced conductance of annealed  $\text{In}_2\text{O}_3$  line arrays. The above results indicated that the interdiffusion at the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface was detrimental to the formation of the degenerate conductive 2DEG, which differs from the previous understanding.<sup>34</sup> In other words, preannealing of the  $\text{In}_2\text{O}_3$  layer prior to deposition of  $\text{Al}_2\text{O}_3$  by ALD suppressed interdiffusion at the interface and was beneficial to the formation of the degenerate conductive interface. Thus, based on the results of the engineering experiments, we concluded that the formation of the degenerate interface was mainly due to the generation of interface defects ( $V_{\text{O}}$ ) rather than the In cation interdiffusion at the interface. Since the conductance of this interface was always kept at a high value when In interdiffusion was suppressed by preannealing of the  $\text{In}_2\text{O}_3$  layer, we believe that the interface defects were confined in an ultrathin interdiffusion layer of the interface. When interdiffusion at the interface was facilitated by the annealing, the enhanced interdiffusion layer upset the equilibrium of interface defects in the ultrathin layer at the interface. This means that building a sharp interface with a high concentration of shallow interface defects is beneficial to obtain such a conductive degenerate interface. Experimentally, we found that pretreatments of annealing and oxygen plasma on the  $\text{In}_2\text{O}_3$  layer provided a more stable fabrication method for preparing this conductive interface.

### 3.4. Processing the Conductive $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$ Interface as a Stable Interface Electrode in Saline Solution.

Finally, we demonstrated an example application of this degenerate interface in a functional electronic device, that is, the fabrication of an  $\text{In}_2\text{O}_3$  line array FET device with the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode (Figure 4a). As shown in Figure 4b, the semiconducting  $\text{In}_2\text{O}_3$  line array in the window served as the electron transport channel, while the other regions with the conductive  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface served as the electrodes. Representative output characteristics of the FET device with interface electrodes at various gate voltages from  $-5$  to 20 V indicated that our degenerate  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface was being used as the interface electrode for the FET device (Figure 4c). Compared to the  $\text{In}_2\text{O}_3$  and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  devices (Figure 4d), the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device showed conductance values between the other devices (Figure 4e), which was consistent with our conductance results above. The transfer curves of the three kinds of FET devices showed that only the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode device



**Figure 5.** Stability of the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode in the PBS solution. (a, b) Stability of the  $\text{In}_2\text{O}_3$  FET device with Pt/Ti as an electrode in (a) air condition and (b) PBS solution when varying gate voltage. (c, d) Stability of the device with the Pt/Ti electrode after covering an  $\text{Al}_2\text{O}_3$  layer in (c) air condition and (d) PBS solution. (e, f) Stability of the device with the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode in (e) air condition and (f) PBS solution. (g) Schematic of stability testing in the PBS solution of the device with the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode. The exponential coordinate of the current was shown in the right section of panels (b) and (d). The gate voltage of all devices was respectively set to 0, 2, 5, 10, and 15 V during the stability test. The thickness of the  $\text{Al}_2\text{O}_3$  layer on the Pt/Ti electrode was set to 5 nm, which is the same as the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode.

exhibited the typical depletion and enhancement modes of current modulation when an electric field was introduced (Figure 4f). In contrast, the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  device always exhibited high conductance, while the  $\text{In}_2\text{O}_3$  device exhibited low conductance, even when an electric field was applied. To clearly show the modulation effect, the “on” current and “off” current were extracted (Figure 4g), and the highest ratio of “on” current to “off” current for the  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode FET device indicated that this FET device had the optimal modulation capability to control the conductance.

Since this interface has an upper  $\text{Al}_2\text{O}_3$  layer that is stable to body fluids, we tested the stability of this device in a saline solution (PBS), which is shown in Figure 5. To evaluate the stability of such an interface electrode in an FET device, the devices with the Pt/Ti electrode and the Pt/Ti electrode covered by an  $\text{Al}_2\text{O}_3$  layer were also fabricated for comparison of performance. In air conditions, all of the devices showed increased current when increasing the gate voltage (Figure 5a,c,e). The devices with the Pt/Ti electrode covered by an

$\text{Al}_2\text{O}_3$  layer and  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode showed a very stable current with increasing test time compared to the device with the Pt/Ti electrode, which is due to the protective effect of the  $\text{Al}_2\text{O}_3$  layer against the molecules in the air. When tested in the PBS solution, the current of the device with the Pt/Ti electrode dropped abruptly, and it still decreased with increasing gate voltage despite being covered by an  $\text{Al}_2\text{O}_3$  layer (Figure 5b,d). In contrast, the device with our interface electrode exhibited an increase in current with increasing gate voltage, as well as the current, remained stable with increasing time, indicating the high stability of the interface electrode in the PBS solution (Figure 5f). Our results prove that the degenerate  $\text{In}_2\text{O}_3/\text{Al}_2\text{O}_3$  interface electrode exhibited high stability in biological saline and showed its potential for applications in functional bioelectronics.

#### 4. CONCLUSIONS

We carried out systematic experiments of oxygen plasma pretreatment and thermal annealing post-treatment to study



the engineering of interface defects and In interdiffusion at the degenerate conductive Al<sub>2</sub>O<sub>3</sub>/In<sub>2</sub>O<sub>3</sub> interface. Interface defects engineered by using oxygen plasma pretreatment on the In<sub>2</sub>O<sub>3</sub> surface prior to Al<sub>2</sub>O<sub>3</sub> deposition indicated that shallow interface defects facilitated the formation of conductive interfaces. Interdiffusion at the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> interface engineered by thermal annealing seemed to degrade the degenerate conductive interface. While past studies have suggested that a semimetallic intermixing layer at the interface promotes the formation of a 2DEG at the In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> interface, we demonstrated a negative effect of interface diffusion on the conductive interface. Based on these findings, we found that pretreatments of annealing and oxygen plasma on the In<sub>2</sub>O<sub>3</sub> layer provided a more stable fabrication method for preparing this conductive interface. After applying this conductive interface as an interface electrode for an FET device, we found that this interface electrode exhibited ultrastability in a biological saline solution. This work lays the foundation for controlling a highly conductive degenerate 2DEG at metal oxide/Al<sub>2</sub>O<sub>3</sub> interfaces and exploring its potential applications in functional bioelectronic devices.

## ■ ASSOCIATED CONTENT

### SI Supporting Information

The Supporting Information is available free of charge at <https://pubs.acs.org/doi/10.1021/acsami.3c03603>.

SEM images (Figure S1); Raman spectra (Figure S2); conductance (Figure S3); band structure (Figure S4); transfer curves (Figure S5); UV response curves of In<sub>2</sub>O<sub>3</sub> and In<sub>2</sub>O<sub>3</sub>/Al<sub>2</sub>O<sub>3</sub> (Figure S6); conductance of the annealed interface (Figure S7); and microscopy images of devices (Figure S8) (PDF)

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Z.Z., T. Yasui, K.N., T.T., and T. Yanagida conceived and designed the overall research plan, experiments, and data analysis. Z.Z., T. Yasui, X.Z., Q.L., S.M., Y.L., A.Y., K.N., T.T., and M.O. developed the setups and performed experiments. X.Z. performed PL spectrum measurements. S.M. and Y.L. performed Raman, AFM, and XPS measurements. A.Y. provided support for the XRD measurement experiments. T. Yasui, T. Yanagida, and Y.B. contributed to conceptualization, funding acquisition, project administration, and supervision. Z.Z. and T. Yasui wrote the manuscript with the input of the other authors.

## Notes

The authors declare no competing financial interest.

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